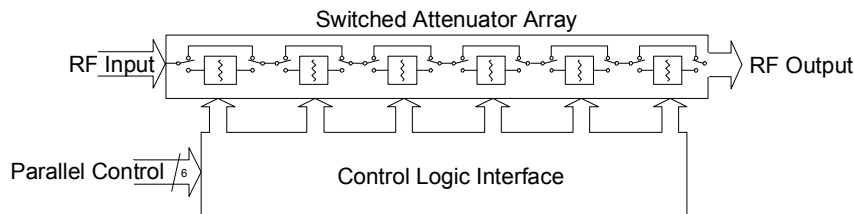


Product Description

This product is a high linearity, 6-bit RF Digital Step Attenuator (DSA) covering a 31.5 dB attenuation range in 0.5 dB steps. The Peregrine 50Ω RF DSA provides a parallel CMOS control interface and it operates on 3-volt to 5-volt supply. It maintains high attenuation accuracy over frequency and temperature and exhibits very low insertion loss and low power consumption. This Peregrine DSA is available in a 4x4 mm 24 lead QFN footprint with an exposed ground paddle.

The SP4309 is manufactured on SIPAT's CMOS process, a patented variation of silicon-on-insulator (SOI) technology on a sapphire substrate, offering the performance of GaAs with the economy and integration of conventional CMOS.

Figure 1. Functional Schematic Diagram



50 Ω RF Digital Attenuator
6-bit, 31.5 dB, DC-4.0 GHz

Features

- Best in class 2.0 kV HBM ESD tolerance
- Low Insertion Loss: 1.6 dB typical
- Attenuation: 0.5 dB steps to 31.5 dB
- High Linearity: Typical 52 dB IP3
- Best in Class Attenuation accuracy
- Parallel programming interface
- Single supply, 3V to 5V operation
- Standard 3V or 5V CMOS control logic independent of supply voltage
- Very low power consumption
- RoHS-compliant 24-lead 4x4 mm QFN

Figure 2. Package Type

4x4 mm 24-Lead QFN

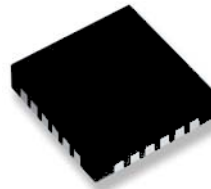


Table 1. Electrical Specifications @ +25°C, V_{DD} = 3.0 V - 5.0 V

Parameter	Test Conditions ⁴	Frequency	Min	Typ	Maximum	Units
Operation Frequency			DC		4000	MHz
Insertion Loss		DC - 2.2 GHz 2.2 - 4.0 GHz	- -	1.6 2.2	2 3.4	dB dB
Attenuation Accuracy	Any Bit or Bit Combination	DC ≤ 1.0 GHz	-	-	±(0.10 + 3% of atten setting), not to exceed +0.20 dB	dB
	Any Bit or Bit Combination	1.0 < 2.2 GHz	-	-	±(0.15 + 3% of atten setting)	dB
	0.5 - 7.5 dB States ³	2.2 < 3.8 GHz	-	0.15	-	dB
	8.0 - 15.5 dB States ³ 16.0 - 31.5 dB States ³	2.2 < 3.8 GHz 2.2 < 3.8 GHz	- -	0.7 1.2	- -	dB dB
1 dB Compression ²		1 MHz - 2.2 GHz	30	32	-	dBm
		2.2 - 4.0 GHz	-	32	-	dBm
Input IP3 ¹	Two-tone inputs +18 dBm	1 MHz - 2.2 GHz	-	52	-	dBm
		2.2 - 4.0 GHz	-	45	-	dBm
Return Loss		DC - 2.2 GHz	15	20	-	dB
		2.2 - 4.0 GHz	10	20	-	dB
Switching Speed	50% of control voltage to 90% of final attenuation level		-	-	1	µs

Notes: 1. Device Linearity will begin to degrade below 5 MHz.

2. Note Absolute Maximum in Table 4.

3. See Figures 12 and 13 for typical attenuation error.

4. Measurements made in a 50 ohm system (see Figure 4, Test Circuit Block Diagram). Resistors (R2, R3, R5, R6, R7) with a value of 10K-ohm are used to decouple the RF path from the control inputs.

Figure 3. Pin Configuration (Top View)

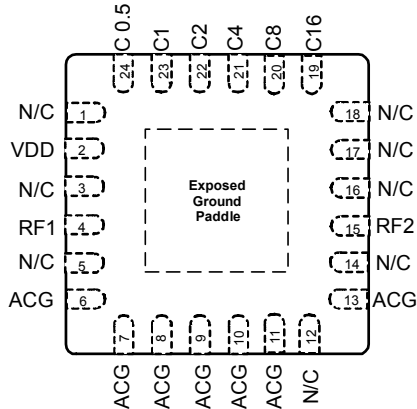


Table 2. Pin Descriptions

Pin No.	Pin Name	Description
1	N/C	No Connect
2	V _{DD}	Power supply pin
3	N/C	No Connect
4	RF1	RF port
5	N/C ⁵	No Connect
6	ACG ⁶	AC Ground connection
7	ACG ⁶	AC Ground connection
8	ACG ⁶	AC Ground connection
9	ACG ⁶	AC Ground connection
10	ACG ⁶	AC Ground connection
11	ACG ⁶	AC Ground connection
12	N/C ⁷	No Connect
13	ACG ⁶	AC Ground connection
14	N/C ⁵	No Connect
15	RF2	RF port
16	N/C ⁵	No Connect
17	N/C ⁵	No Connect
18	N/C ⁵	No Connect
19	C16	Attenuation control bit, 16 dB
20	C8	Attenuation control bit, 8 dB
21	C4	Attenuation control bit, 4 dB
22	C2	Attenuation control bit, 2 dB
23	C1	Attenuation control bit, 1 dB
24	C0.5	Attenuation control bit, 0.5 dB
Paddle	GND	Ground for proper operation

Notes: 5. For improved RF performance these No Connect pins can be connected to RF ground.

6. Pins can either be grounded directly or through coupling capacitors

7. Pin can either be grounded or No Connect

Exposed Solder Pad Connection

The exposed solder pad on the bottom of the package must be grounded for proper device operation.

Table 3. Operating Ranges

Parameter	Min	Typ	Max	Units
V _{DD} Power Supply Voltage	3.0	3.3	5.5	V
I _{DD} Power Supply Current		100	250	μA
P _{in} Input power (50Ω)			+24	dBm

Table 4. Absolute Maximum Ratings

Symbol	Parameter/Conditions	Min	Max	Units
V _{DD}	Power supply voltage	-0.3	6.0	V
V _I	Voltage on any DC input	-0.3	6.0	V
T _{ST}	Storage temperature range	-65	150	°C
T _{OP}	Operating temperature range	-40	85	°C
P _{IN}	Input power (50Ω)		30	dBm
V _{ESD}	ESD voltage (Human Body Model)		2000	V

Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS™ device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the rate specified in Table 4.

Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS™ devices are immune to latch-up.

Table 5. Control Voltage

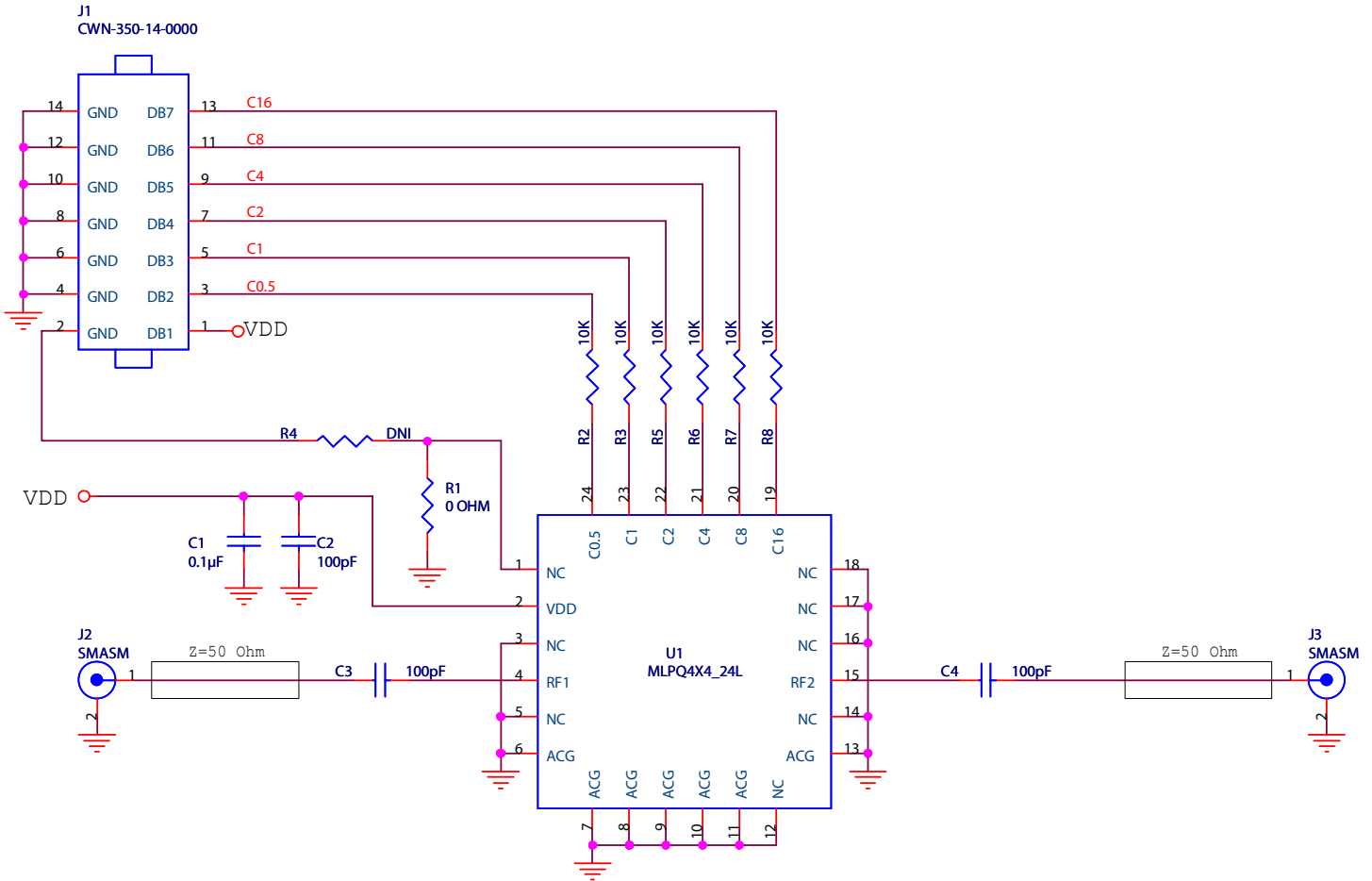
State	Bias Condition
Low	0 to +1.0 Vdc at 2 μA (typ)
High	+2.0 to +5 Vdc at 10 μA (typ)

The standard 3V or 5V CMOS control logic is independent of supply voltage.

Table 6. Truth Table

C16	C8	C4	C2	C1	C0.5	Attenuation State
1	1	1	1	1	1	Reference Loss (IL)
1	1	1	1	1	0	0.5 dB
1	1	1	1	0	1	1 dB
1	1	1	0	1	1	2 dB
1	1	0	1	1	1	4 dB
1	0	1	1	1	1	8 dB
0	1	1	1	1	1	16 dB
0	0	0	0	0	0	31.5 dB

Figure 4. Test Circuit Block Diagram



ECT BP050-0024UJ03 4x4
MLP 24 Ld Socket

Evaluation Kit

The Digital Attenuator Evaluation Kit board was designed to ease customer evaluation of the SP4309 Digital Step Attenuator. Connect J2 by mini clip to Vdd to power the IC. Connect J8 by mini clip to power the evaluation board support circuits. The control bits for the six parallel data inputs (C0.5 to C16) are controlled using S2-S7 to select bits or bit combinations. This allows any attenuation setting to be specified as shown in Table 6.

The de-embed trace (J6 to J7) estimates the PCB insertion loss for removal from the evaluation board measurement data.

To evaluate using customer software, J1 can be installed using a standard 0.100 IDC header (some circuit modification required, see schematic).

The ability to supply different voltages for the Control circuitry (using J8) and IC Vdd (using J2) circuits allows for evaluation of circuits using different control vs. supply voltages.

Figure 5. Evaluation Board Layout

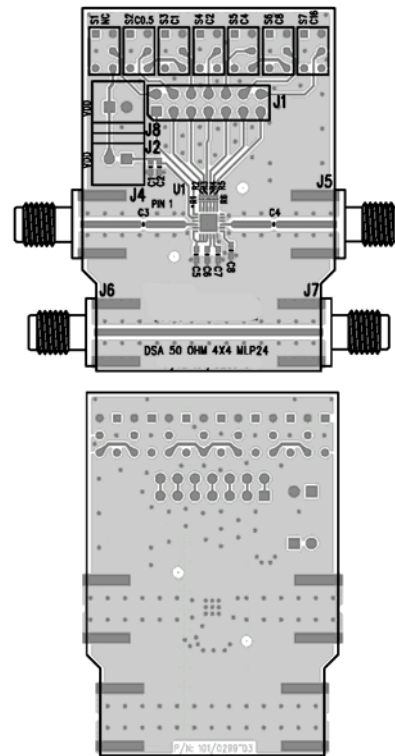
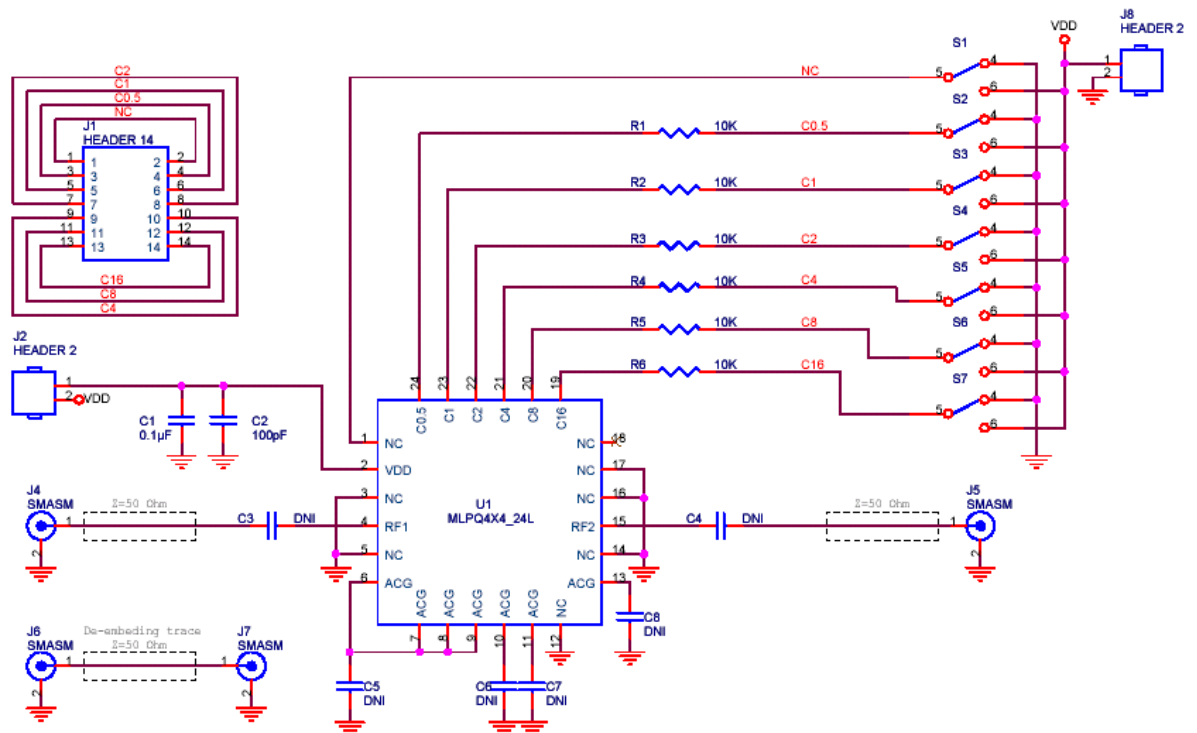


Figure 6. Evaluation Board Schematic



Typical Performance Data

Figure 7. Insertion Loss, $V_{dd} = 3.0\text{ V}$

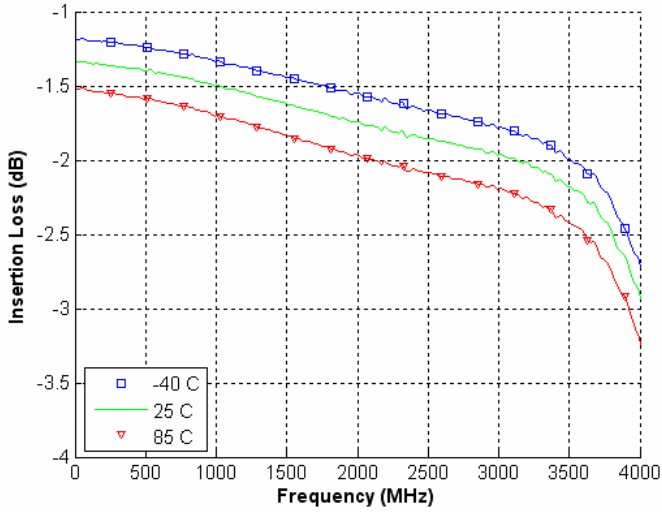


Figure 8. Attenuation at Major Steps

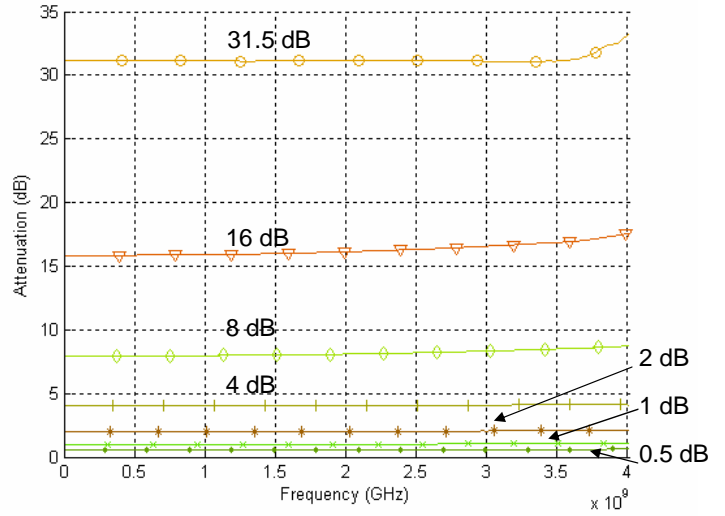


Figure 9. Input Return Loss at Major Attenuation Steps

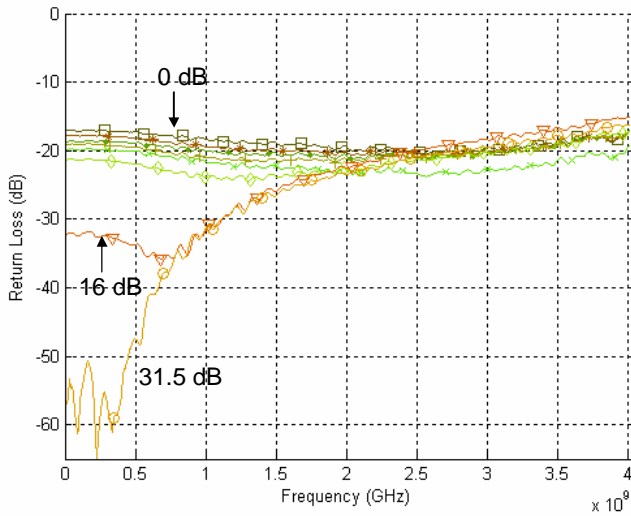
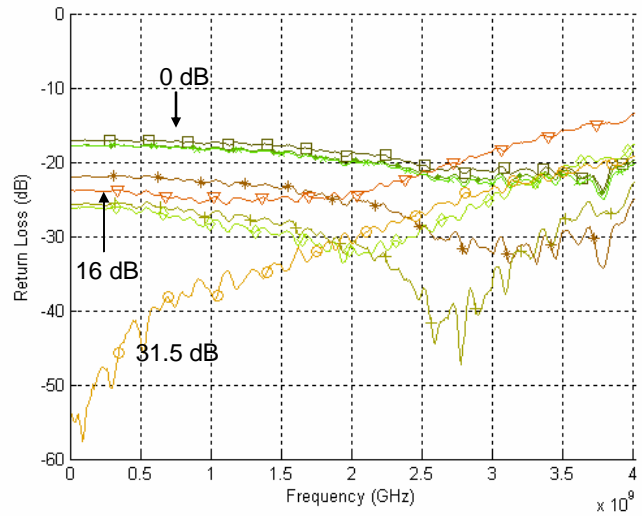


Figure 10. Output Return Loss at Major Attenuation Steps



Typical Performance Data

Figure 11. Attenuation Error Vs. Frequency

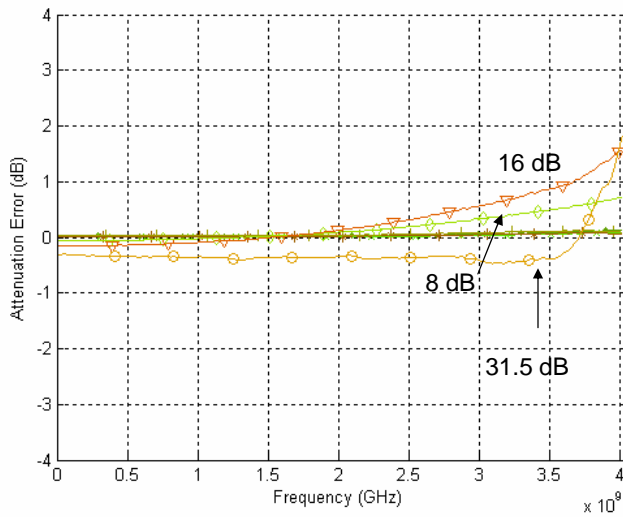


Figure 12. Attenuation Error vs. Setting: Low Frequency

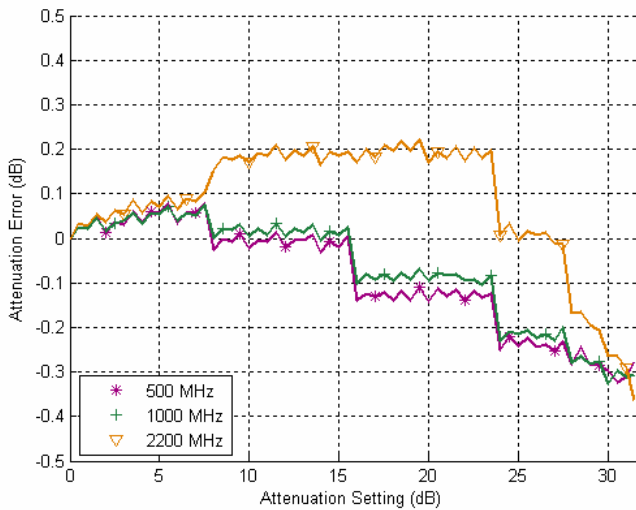


Figure 13. Attenuation Error vs. Setting: High Frequency

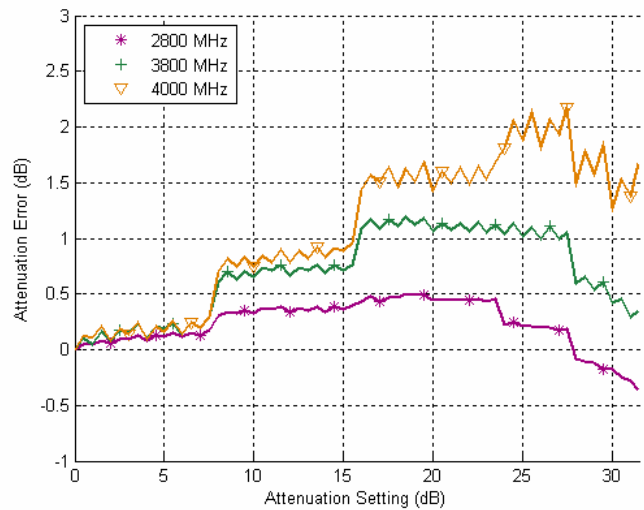
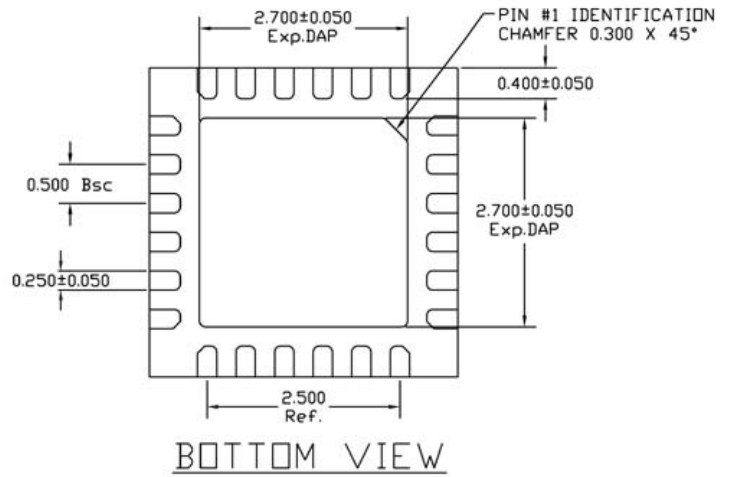
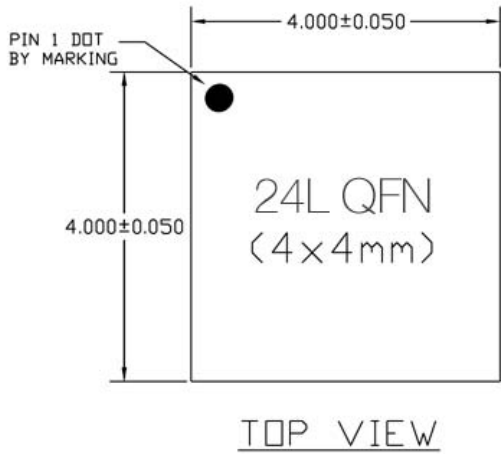


Figure 16. Package Drawing



		QFN 4x4 mm
A	MAX	0.900
	NOM	0.850
	MIN	0.800

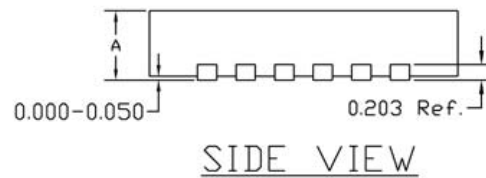
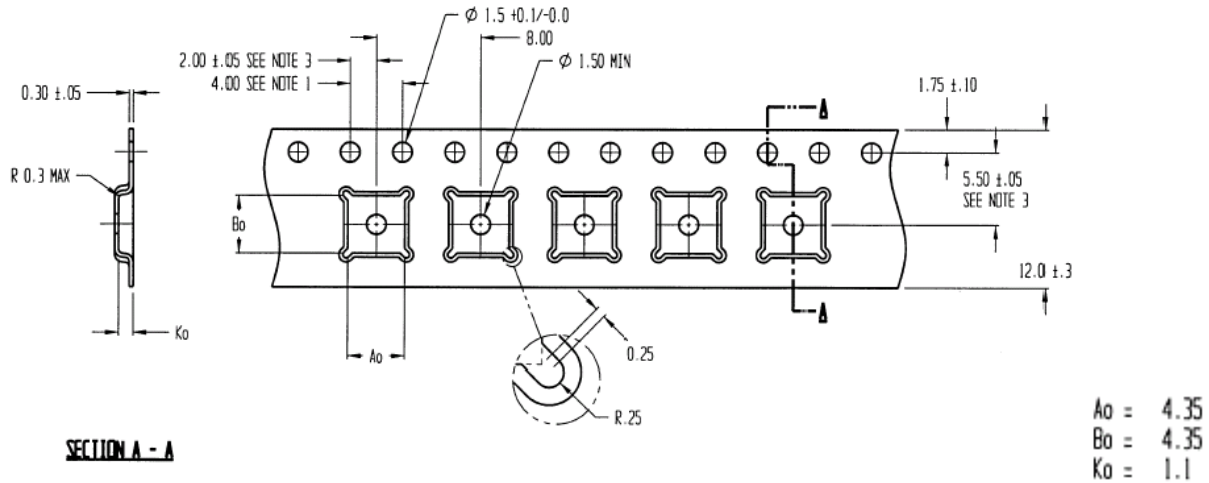


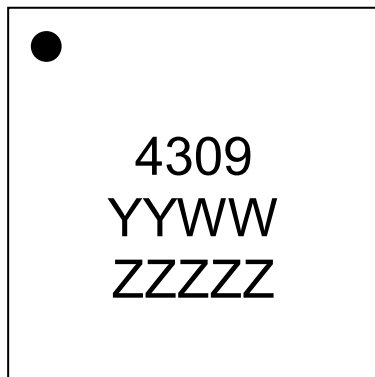
Figure 17. Tape and Reel Drawing



NOTES:

1. 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE ± 0.2
2. CAMBER IN COMPLIANCE WITH EIA 481
3. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE

Figure 18. Marking Specifications



YYWW = Date Code
ZZZZZ = Last five digits of Lot Number